



STD30NF03LT

N-CHANNEL 30V - 0.017Ω - 30A DPAK

STripFET™II MOSFET

Table 1: General Features

TYPE	V _{DSS}	R _{DS(on)}	I _D (1)
STD30NF03LT	30 V	< 0.025Ω	30 A

- TYPICAL R_{DS(on)} = 0.017Ω
- LOGIC LEVEL GATE DRIVE

DESCRIPTION

This MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING

Figure 1: Package

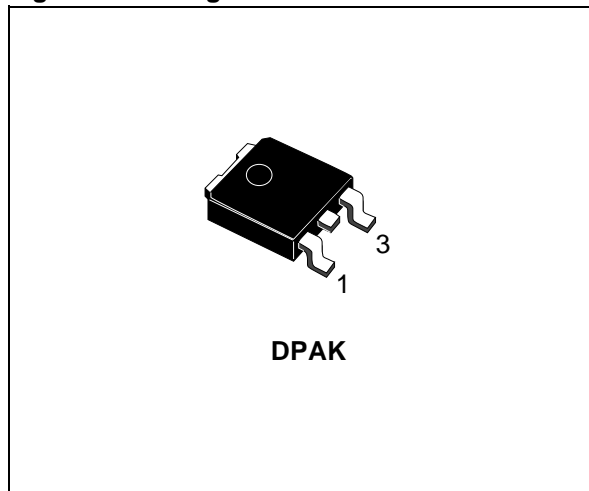


Figure 2: Internal Schematic Diagram

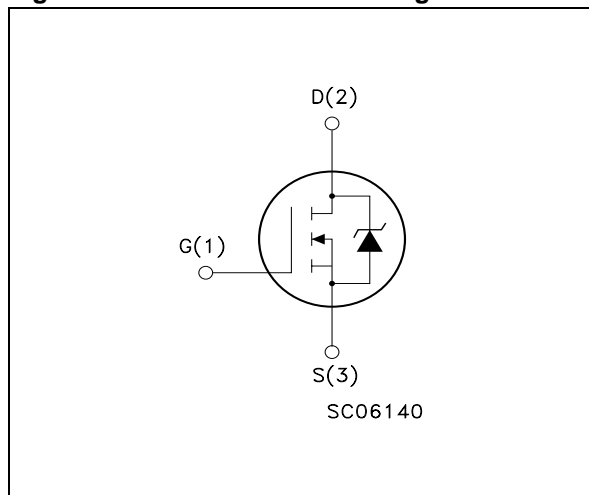


Table 2: Order Codes

Part Number	Marking	Package	Packaging
STD30NF03LTT4	D30NF03LT	DPAK	TAPE & REEL

Table 3: Absolute Maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source Voltage ($V_{GS} = 0$)	30	V
V_{DGR}	Drain-gate Voltage ($R_{GS} = 20\text{ k}\Omega$)	30	V
V_{GS}	Gate- source Voltage	± 20	V
I_D	Drain Current (continuous) at $T_C = 25^\circ\text{C}$	30	A
I_D	Drain Current (continuous) at $T_C = 100^\circ\text{C}$	21	A
$I_{DM}(\bullet)$	Drain Current (pulsed)	120	A
P_{TOT}	Total Dissipation at $T_C = 25^\circ\text{C}$	50	W
	Derating Factor	0.33	W/ $^\circ\text{C}$
dv/dt (1)	Peak Diode Recovery voltage slope	4	V/ns
E_{AS} (2)	Single Pulse Avalanche Energy	450	mJ
T_{stg}	Storage Temperature	– 55 to 175	$^\circ\text{C}$
T_j	Operating Junction Temperature		

(●) Pulse width limited by safe operating area

(1) $I_{SD} \leq 30\text{A}$, $di/dt \leq 400\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$, $T_j \leq T_{JMAX}$.

(2) Starting $T_j = 25^\circ\text{C}$, $I_D = 15\text{A}$, $V_{DD} = 25\text{V}$

Table 4: Thermal Data

Rthj-Case	Thermal Resistance Junction-Case	3.0	$^\circ\text{C}/\text{W}$
Rthj-amb	Thermal Resistance Junction-ambient Max	100	$^\circ\text{C}/\text{W}$
T_l	Maximum Lead Temperature For Soldering Purpose	275	$^\circ\text{C}$

Table 5: Avalanche Characteristics

Symbol	Parameter	Max Value	Unit
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_j max)	40	A
E_{AS}	Single Pulse Avalanche Energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 15\text{V}$)	2.3	J

ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^\circ\text{C}$ UNLESS OTHERWISE SPECIFIED)**Table 6: On /Off**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0$	30			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$			1	μA
		$V_{DS} = \text{Max Rating}$, $T_C = 125^\circ\text{C}$			10	μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	1	1.7	2.5	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 6\text{ V}$, $I_D = 15\text{ A}$		0.025	0.035	Ω
		$V_{GS} = 10\text{ V}$, $I_D = 15\text{ A}$		0.017	0.025	Ω

ELECTRICAL CHARACTERISTICS (CONTINUED)

Table 7: Dynamic

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g_{fs} (1)	Forward Transconductance	$V_{DS} \geq 15\text{ V}$, $I_D = 15\text{ A}$		30		S
C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$		750		pF
C_{oss}	Output Capacitance			280		pF
C_{rss}	Reverse Transfer Capacitance			70		pF

Table 8: Switching On

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 15\text{ V}$, $I_D = 15\text{ A}$		15		ns
t_r	Rise Time	$R_G = 4.7\Omega$, $V_{GS} = 6\text{ V}$ (see test circuit, Figure 3)		30		ns
Q_g	Total Gate Charge	$V_{DD} = 15\text{ V}$, $I_D = 30\text{ A}$, $V_{GS} = 6\text{ V}$		13	18	nC
Q_{gs}	Gate-Source Charge			5.5		nC
Q_{gd}	Gate-Drain Charge			5		nC

Table 9: Switching

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off-Delay Time	$V_{DD} = 15\text{ V}$, $I_D = 15\text{ A}$ $R_G = 4.7\Omega$, $V_{GS} = 6\text{ V}$ (see test circuit, Figure 3)		20		ns
t_f	Fall Time			10		ns

Table 10: Source Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current				30	A
I_{SDM} (2)	Source-drain Current (pulsed)				120	A
V_{SD} (1)	Forward On Voltage	$I_{SD} = 30\text{ A}$, $V_{GS} = 0$			1.5	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 30\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 20\text{ V}$, $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5)		35		ns
Q_{rr}	Reverse Recovery Charge			38		nC
I_{RRM}	Reverse Recovery Current			2.5		A

(1) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

(2) Pulse width limited by safe operating area.

Figure 3: Safe Operating Area

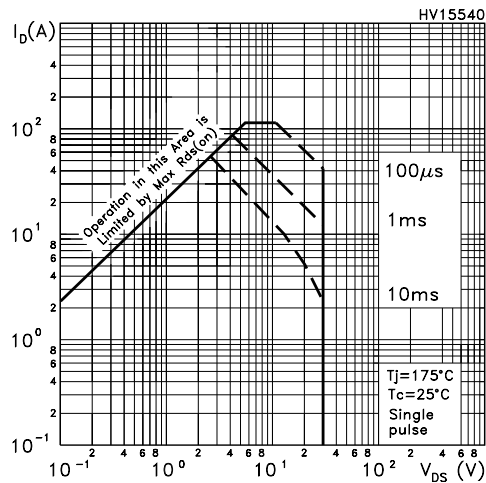


Figure 4: Output Characteristics

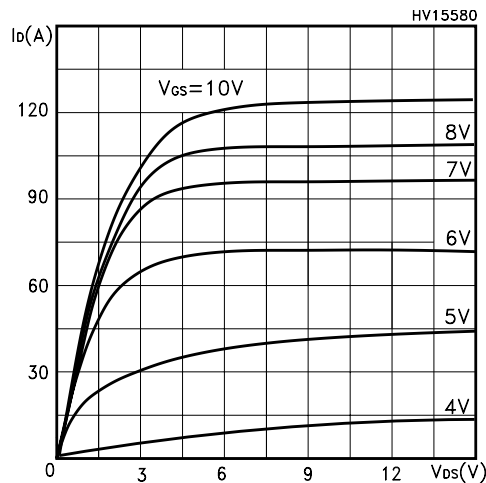


Figure 5: Transconductance

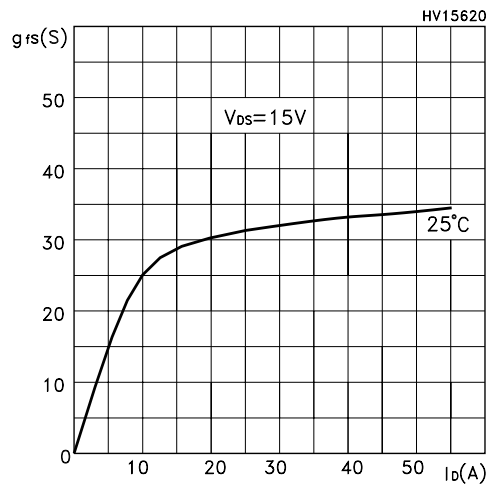


Figure 6: Thermal Impedance

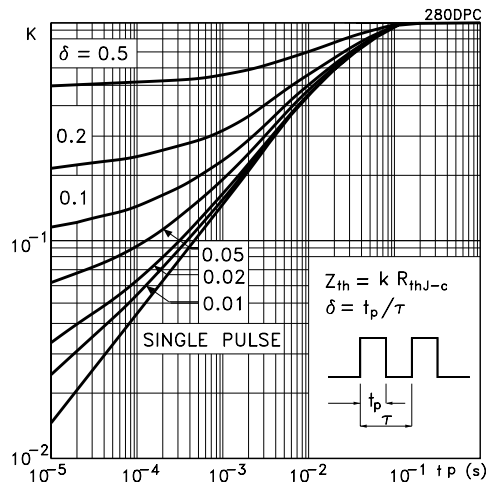


Figure 7: Transfer Characteristics

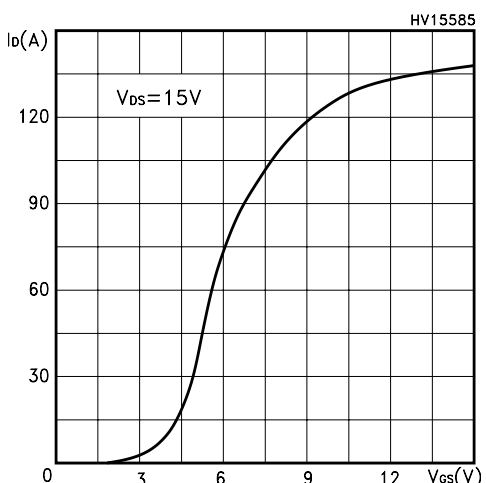


Figure 8: Static Drain-source On Resistance

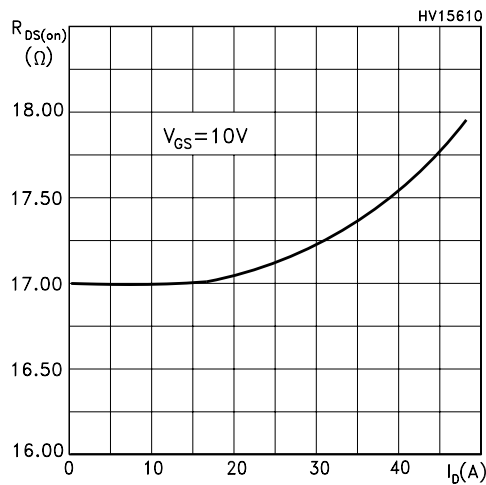


Figure 9: Gate Charge vs Gate-source Voltage

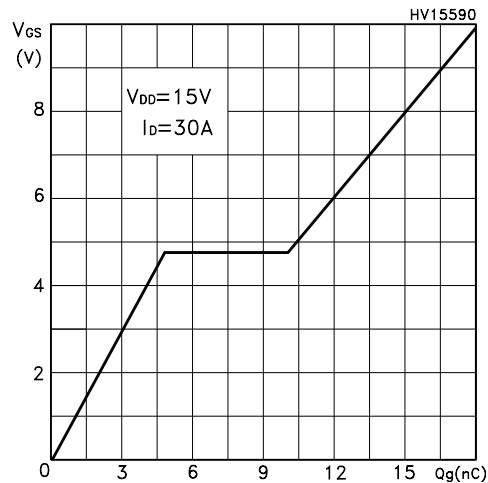


Figure 10: Normalized Gate Threshold Voltage vs Temperature

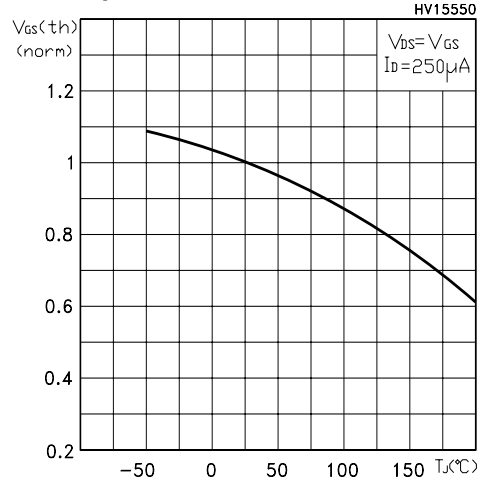


Figure 11: Capacitance Variations

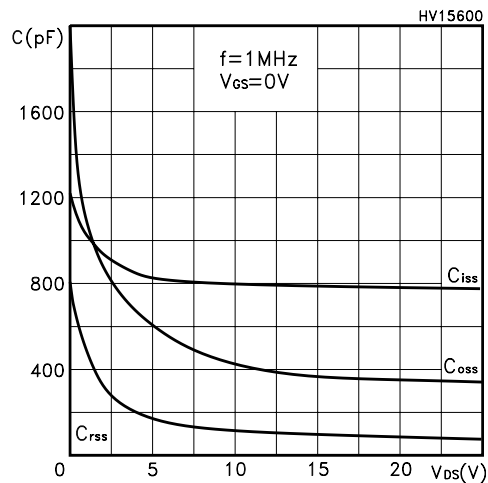


Figure 12: Normalized On Resistance vs Temperature

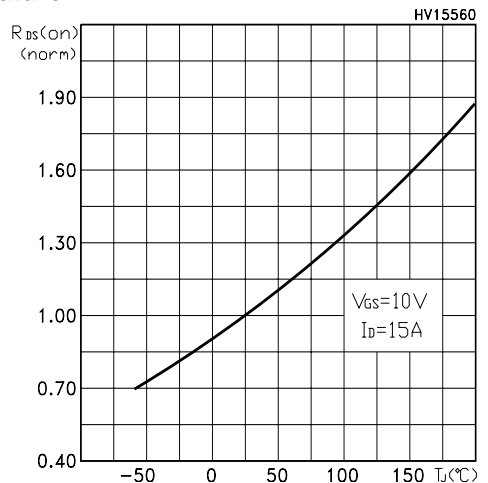


Figure 13: Normalized BVDSS vs Temperature

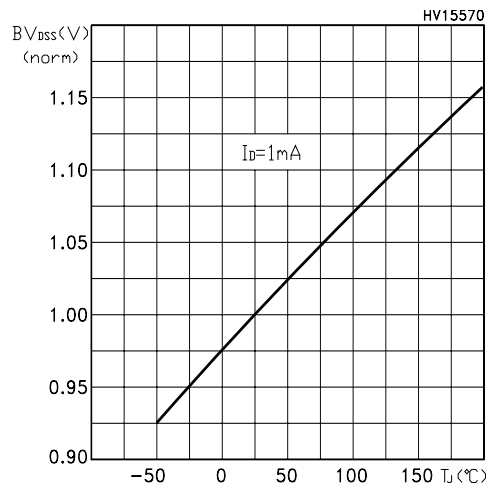


Figure 14: Switching Times Test Circuit For Resistive Load

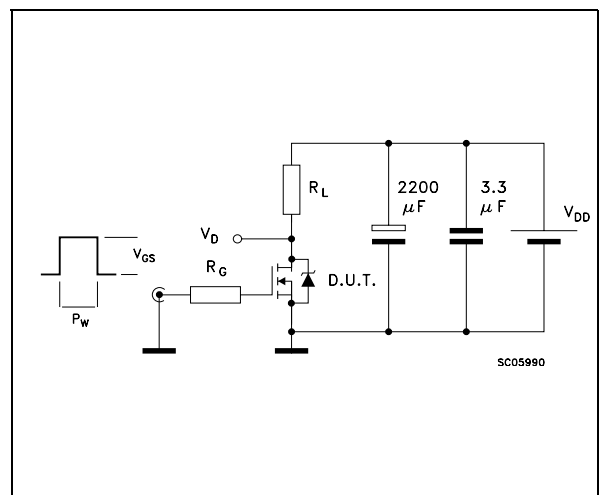


Figure 15: Test Circuit For Diode Recovery Times

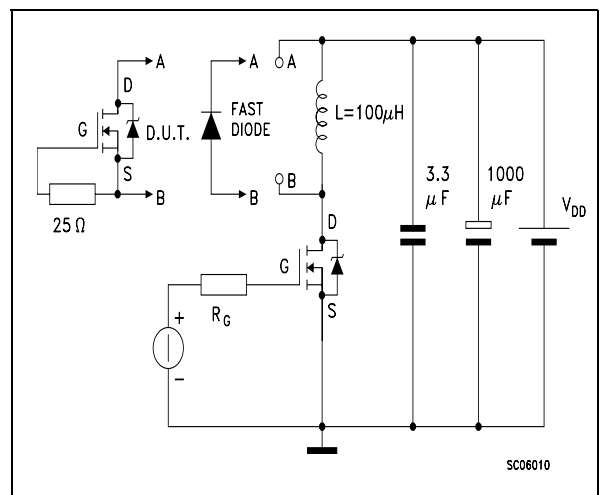
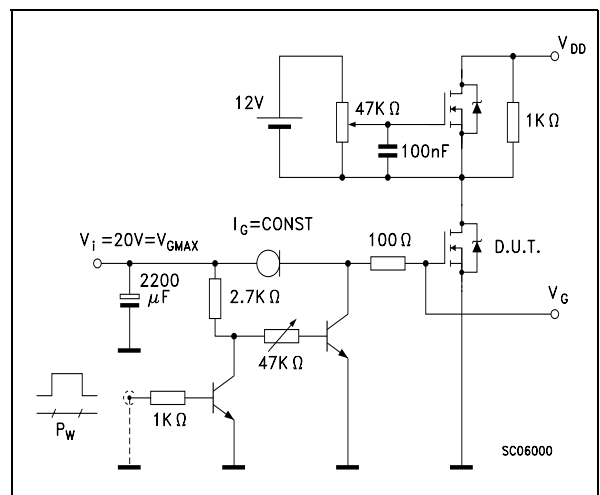
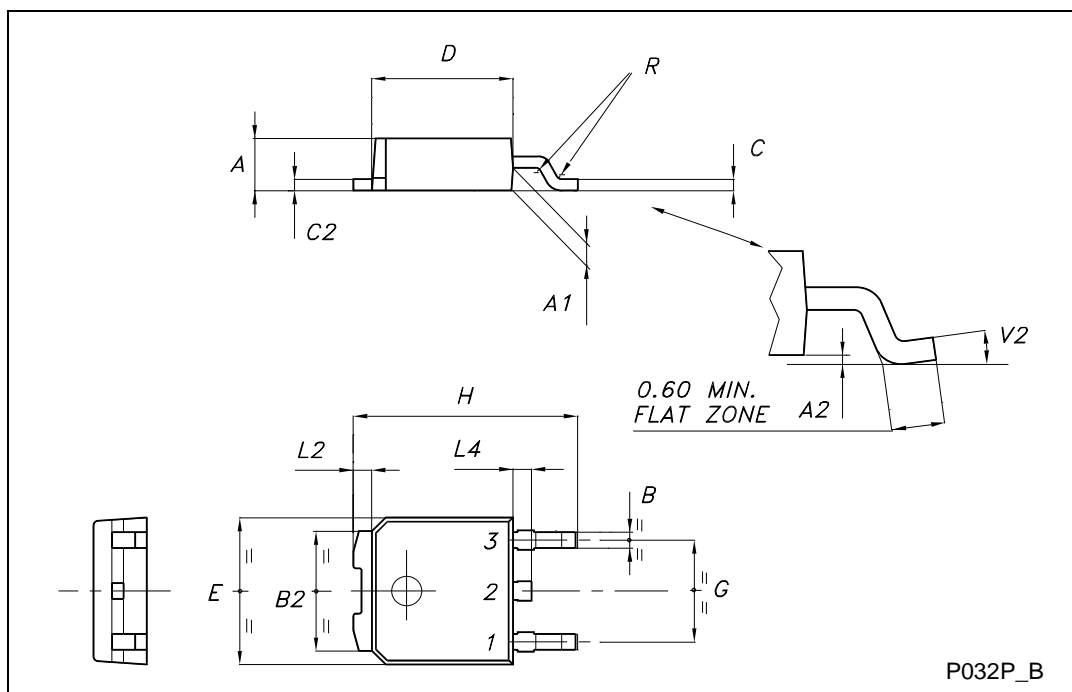


Figure 16: Gate Charge Test Circuit

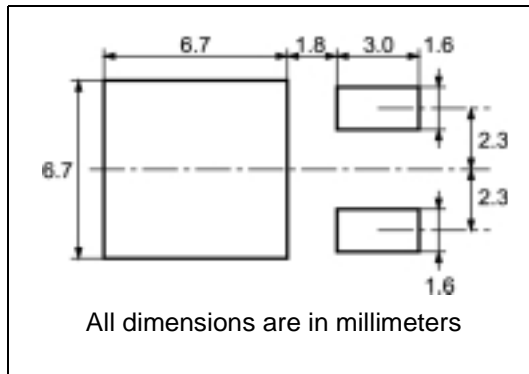


TO-252 (DPAK) MECHANICAL DATA

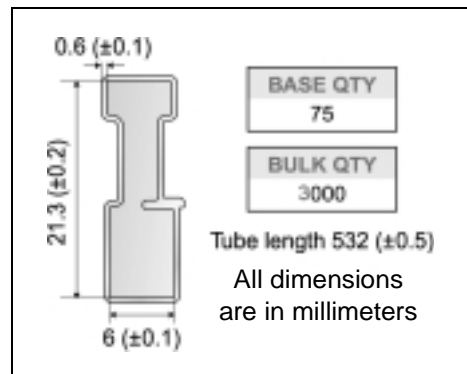
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
C	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°



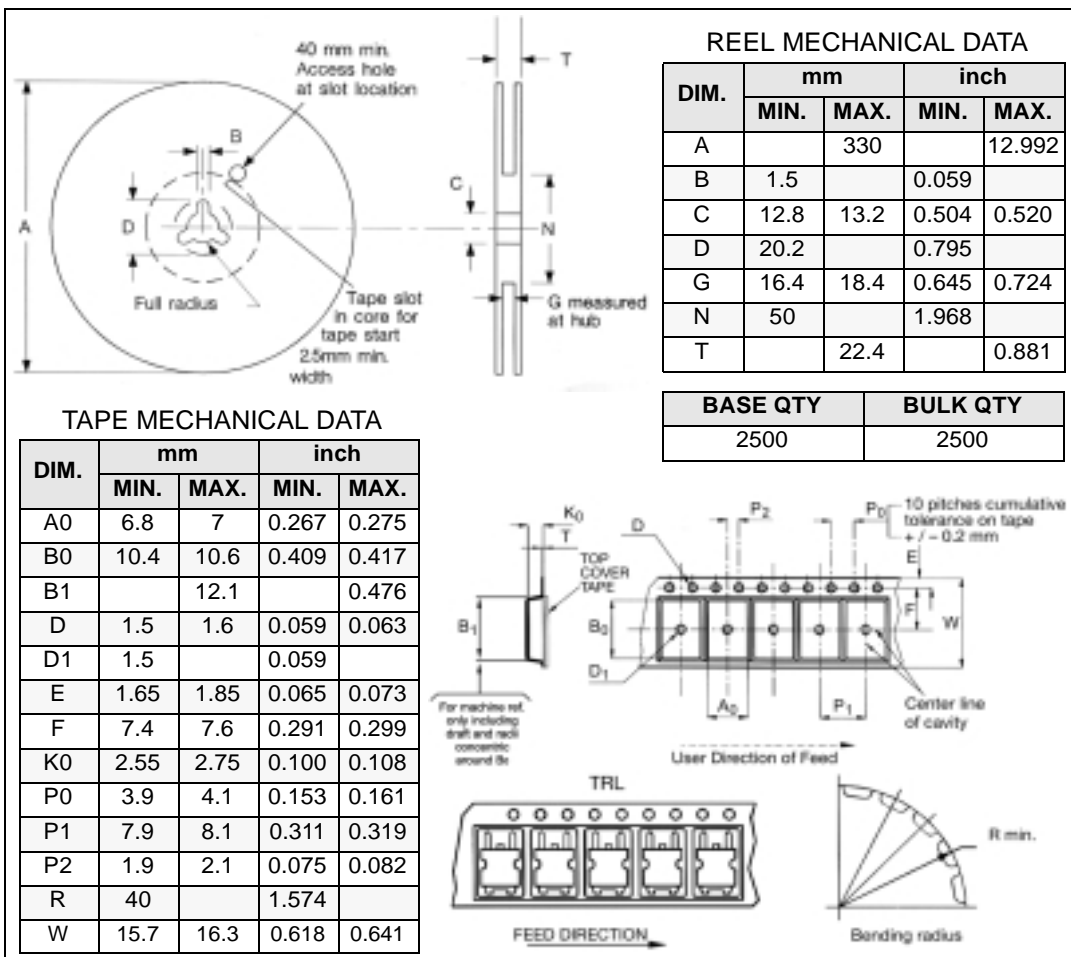
DPAK FOOTPRINT



TUBE SHIPMENT (no suffix)*



TAPE AND REEL SHIPMENT (suffix "T4")*



* on sales type

Table 11: Revision History

Date	Revision	Description of Changes
15-Feb-2005	1	First Release.

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